

BEST

Technology



Company Profile

Since established in June 2006, Best Technology Co., Limited. was dedicated to become the best suitable partner of specific, advanced, high-precision printed circuit boards, include but not limited to Metal Core PCB (MCPCB) such as aluminum PCB, COB MCPCB, copper PCB, Ceramic PCB, Heavy copper board (up to 20 OZ), HDI (1+N+1, 2+N+2, 3+N+3), mixed layers, high TG, HDI, high Frequency (Rogers, Taconic), Impedance controlled board, and so on.

What we provide is not only PCB manufacturing, but also including PCB duplicating, Engineering & process design, components management & sourcing solution, PCB in house assembly & full system integration.

Quality is the core of our company. All of engineer & vital department guys has more than five years' experience in PCB industry. We follow up not only the default PCB standard (IPC), but also customers' special request.

All the manufacturing are strictly follow the operation procedures stipulated in ISO9001:2008 in respect to material purchasing, product manufacturing, testing, packing, marketing, etc. All the order placed with us is money-refund-guaranteed.

We will be glad to grow up together with our customers! Welcome to visit us today to enjoy our service!



Products & Service

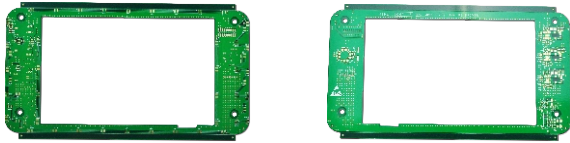
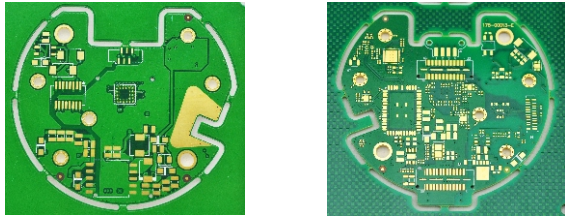
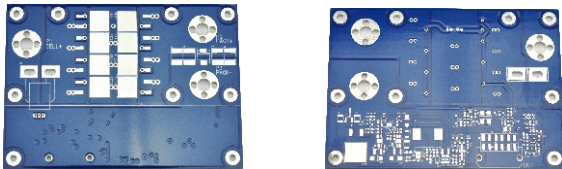
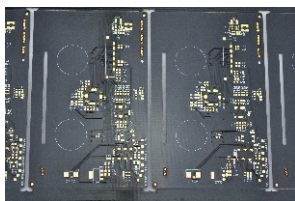
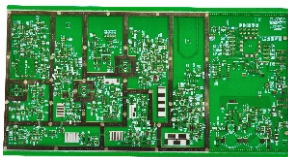
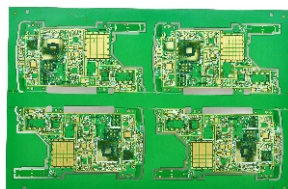
Products:

- 1.FR4 PCB: Standard PCB: 1-20 layers; HDI (1+N+1, 2+N+2, 3+N+3); Heavy Copper (up to 20 OZ); extra thin PCB (0.20mm).
- 2.MCPCB: Aluminum and Copper core PCB, 1-10 layers.
- 3.Ceramic PCB: Alumina, AlN, BeO substrate, 1-8 layers; Thick film, DCB (DBC)technology.
- 4.Rigid-flex circuits: 2-10 layers.
- 5.Flexible Circuit: 1-10 layers.

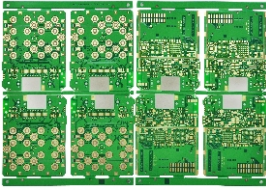
Service:

- Mass production: (Small, medium, big volume)
- Prototype/samples
- Quick-turn service
- PCB Assembly service
- Turn-key service (PCB+Components+Assembly)

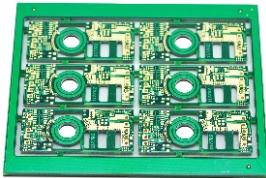


FR4 PCB**BPM13265-B:** 6L 1.6mm FR4 PCB, TG170,2OZ(all layers), ENIG, green oil.**BPM13028:** 6L HDI (1+4+1) 1.6mm 170Tg, ENIG, Green oil.**BPM12109:** 2L 2.0mm 10 OZ both layers, ENIG, blue oil.**BPM13098:** 6L 0.8mm FR4 PCB PCB, 1OZ, ENIG, black oil.**BPM12019:** 6L 1.6mm FR4 PCB, Rogers4003+FR4, 1OZ, ENIG, green oil.**BPM10164:** 8L HDI(2+4+2) 1.0mm PCB, ENIG, 50 & 100 Ohm impedance control.

FR4 PCB



BPM13244: 6L HDI 4/4mil, 0.1mm Via, 0.8mm drill depth control (L1-L3, L6-L3), ENIG, green oil.



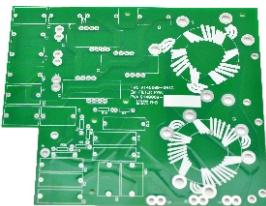
BPM12201: 20L 3.0mm FR4 PCB 2OZ all layers, ENIG, green oil.



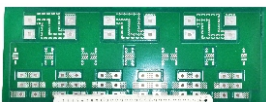
BPM12138-B: 6L FR4 3.2mm 2OZ(outer) 1OZ(inner), ENIG, Green oil, countersink hole.



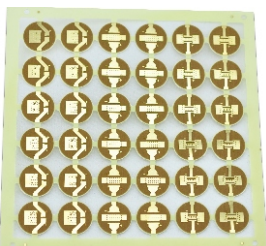
BPM13061: 8L FR4 2.0mm 3OZ(all layers), HAL(LF), green oil.



BPD11129: 2L 2.4mm 10 OZ both layers, HAL(LF), green oil.

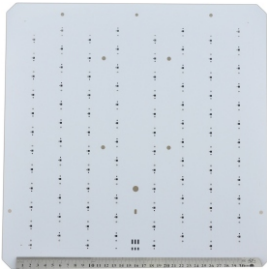


BPD12205: 2L 3.0mm PCB, 20 OZ both layers, 230x550mm, HAL(LF), green oil.



BPD12202: 2L extra thin FR4 PCB, 0.15mm, ENIG, no soldermask.

MCPCB



BAS12061: 1L aluminum Core PCB 1.6mm 2OZ 2W/m-K, white oil, HAL(LF), 345x355mm, for street light LED.



BAS12037: 1L aluminum Core PCB 1.8mm 1OZ 1W/m-K, white oil, HAL(LF).



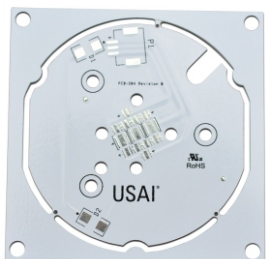
BAS12123: 1L aluminum Core PCB 2mm 2OZ, 2W/m-k, ENIG, White oil.



BAS10128-A: 1L aluminum Core PCB 2.0mm 2OZ 2W/m-K, white oil, HAL(LF).

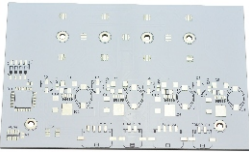


BAS13198: 1L aluminum Core PCB 1.6mm 2OZ 2W/m-K, white oil, HAL(LF).



BAS13090: 1L aluminum core PCB, 1.6mm 1OZ 3W/m-K, HAL(LF), white oil.

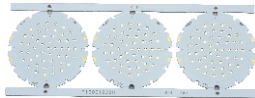
MCPCB



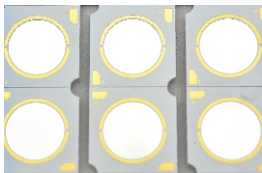
BAD12063: 2L aluminum core PCB, 1OZ, 1.6mm, 1W/m-K, HAL(LF), white oil.



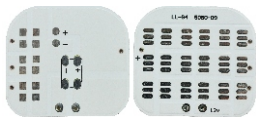
BAD12197-B: Double sided aluminum core PCB 1.6mm 1OZ, 2W/m-K, HAL(LF), white oil.



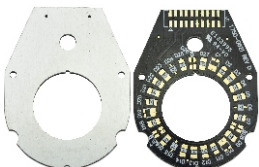
BAD12206: 2L COB aluminum Core PCB, 1.6mm 1OZ 1W/m-K, white oil, ENIG.



BAD12207: 2L COB aluminum Core PCB (Mirror aluminum), 1.6mm 1OZ 1W/m-K, white oil, ENIG.



BAD12208: Double sided aluminum core PCB 1.6mm 1OZ, 1W/m-K, HAL(LF), white oil..

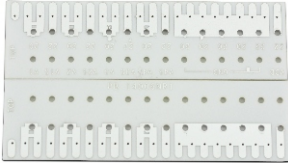


BAM12083: 4L aluminum core PCB 1.6mm 1OZ ENIG, black oil, 2W/m-K.

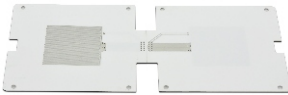
Ceramic PCB



BCS13068: 0.635mm Alumina, double layers, Ag Palladium.



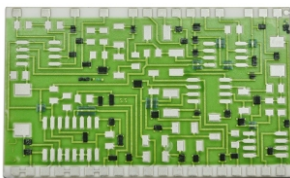
BCD12096: 1.0mm Alumina, double layers, Ag Palladium, PTH + NPTH.



BCD12150: 0.635mm Alumina, double layers, Ag Palladium, PTH + NPTH.

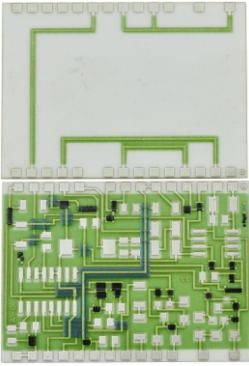


BCD13252: 0.635mm Alumina, double layers, Au Palladium + Ag Palladium, glass glaze, NPTH.

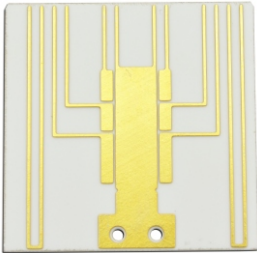


BCMXXX01: Alumina, 4 layers, Ag palladium, resistors bonded.

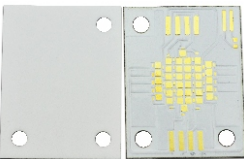
Ceramic PCB



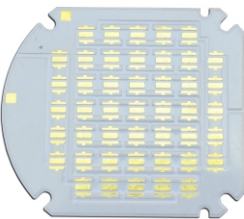
BCMXXX02: Alumina, 4 layers, Ag palladium, resistors bonded.



BCS11111: 1.0mm Alumina, 1 layers, 0.3mm copper, 3 micron gold.

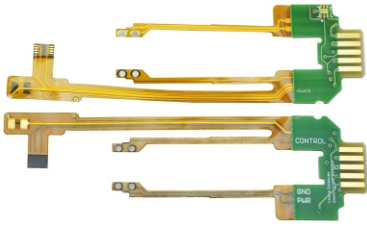


BCS11106: 1.0mm Alumina, 1 layers, 0.1mm copper, 3 micron gold.



BCS12188: 0.635mm Alumina, 1 layers, 0.1mm copper, 3 micron gold, white soldermask.

Rigid-flex circuits



BFR13073-B or: 4L Rigid-flex, 30u" Hard Gold finger,



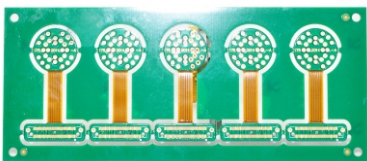
BFR11041: 3L Rigid-flex, 30u" Hard Gold finger



BFR12210: 3L rigid-flex, 1.6mm 1OZ ENIG,



BFR12209: 4L Rigid-flex 1.6mm,1OZ, ENIG

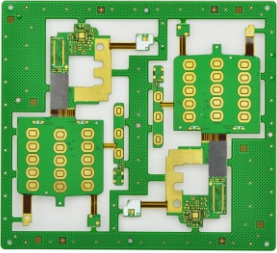


BFR13009: 6L Rigid-flex 1.6mm,1OZ, 170Tg, ENIG

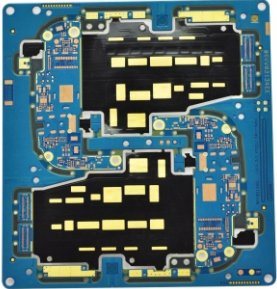
Rigid-flex circuits



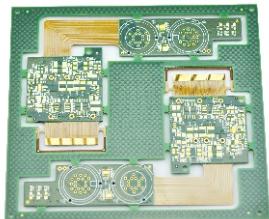
BFR08201: 14L Rigid-flex 2.0mm, 4L FR4+2+2+2L FPC + 4L FR4, ENIG



BFR13306: 4L Rigid-flex for mobile phone, 0.60mm, 1LFR4+2L FPC+1L FR4, 3mil/3mil



BFR13307: 4L Rigid-flex, black electromagnetic membrane, 0.60mm, 1LFR4+2L FPC+1L FR4, 3mil/3mil



BFR12211: 6L Rigid-flex (2PCB+2FPC+2PCB), Gold finger

Flexible circuits



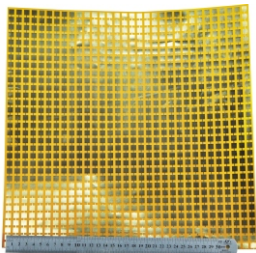
BFS09303: 1L FPC 1OZ, Embossing contact point, ENIG.



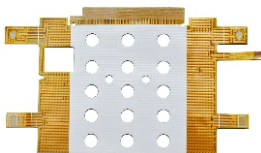
BFS10003-B: 1L FPC, 2 mil PI+4 OZ, ENIG.



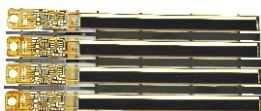
BFS11002: 1L FPC, size: 1510*7.5mm, ENIG, soldermask, T=0.05mm.



BFD13095: 2L FPC, 35/25 RA OZ Cu, size: 374.6x454.64mm/pcs, ENIG.



BFD9120-B: 2L FPC, 1/3OZ Cu adhesiveless, T=0.1mm, ENIG,, PI+FR4 stiffener, Polyimide+white oil.



FPCB-10514: 2L FPC, 35/25 RA Cu, ENIG, carbon ink (resistance control).



BFD12069: 2L FPC, 18/25 RA Cu, Tin Immersion, impedance control 50 Ohm.

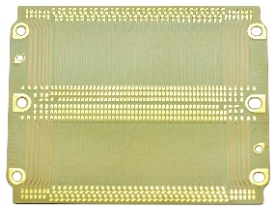
Flexible circuits



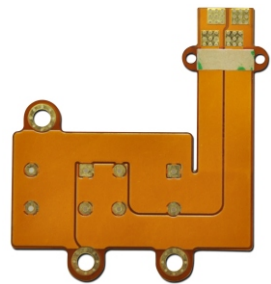
BFD12301: 2L FPC, 35/25 RA Cu, Via filled, impedance control 50 Ohm, 1,545*19mm.



BFS12302: 1L Flex cable, 1 OZ Cu, 1,345*36mm.



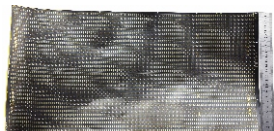
BFM08302: 4L FPC, 1/2 RA Cu adhesiveless, 50 micron hard gold, impedance control 50 Ohm +/-10%.



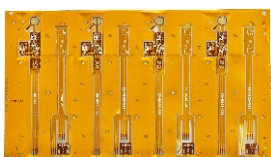
BFM13172: 4L FPC 35/25 RA Cu, FR4+PI stiffener, 3M 467, ENIG.



BFD12303: Dual access FPC for automobile, Nickel plating, 4OZ, laser cutting slot size tolerance +/-0.02mm, 234X600mm



BFD12304: 2L FPC for LED display, black coverlay, ENIG

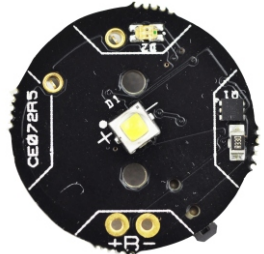


BFD12305: 2L FPC for electronic pen, precision hole diameter and alignment, laser cutting hole, ENIG

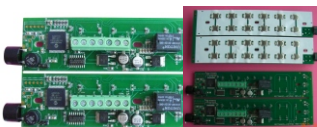
PCBA



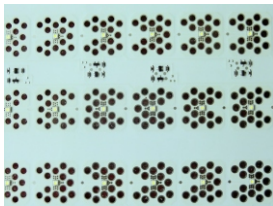
BPD13205: 0.15mm extra thin PCB + Components + Battery



BPD9042: 2L FR4 PCB + Components+ Cree LED+ metal dome array



BPD10093: 2L FR4 PCB + Components + metal dome array



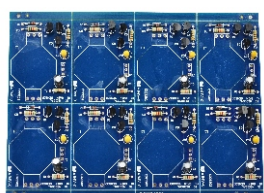
BPD12140: 2L FR4 PCB +Components+ LED (Osram). Street light



BAS13198: MCPCB+Cree LED (XPG)+Wango Connector

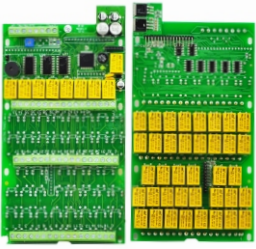


BAS12179: MCPCB+Cree LED (XTE)+ TE Connector



BPD13176: 2L FR4 PCB + DIP Components

PCBA



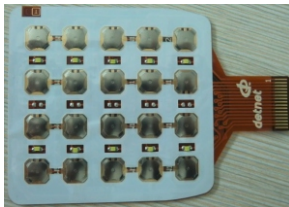
BPD11157: 2L FR4 PCB + SMD components + DIP Components



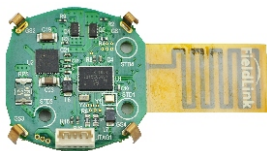
BPM12078-B: 3L FR4 PCB + Components + LED (DIP)



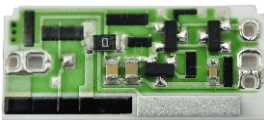
BFD12193: 2L FPC, medical products



BFD13016-B: 2L FPC + Components + metal dome array



BFR13159: 4L Rigid-flex PCBA



BCS13312: 1L Ceramic PCB + Components

Factory Tour 1



CNC-Cutting



CNC Drilling (Hitch)



Laser Drilling



Cu II Auto-line



Cu I Auto-line



D/F Exposure Machine



D.E.S Line



Brown-Oxide Line



Auto Optic Inspection

Factory Tour 2



Riveting Machine



Location Hole-Inner layer



Traditional Laminator



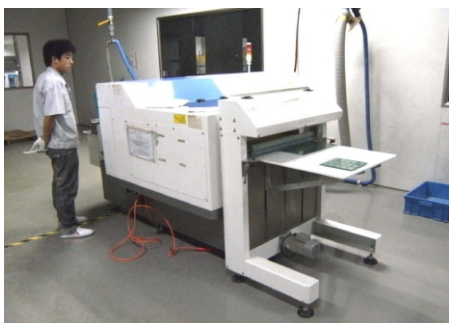
Gyraton /Turning system



CNC Router



ENIG Auto-Line



Auto CNC V-Cut Machine



Automatic Soldermask Machine



OSP Line

Quality Measurement



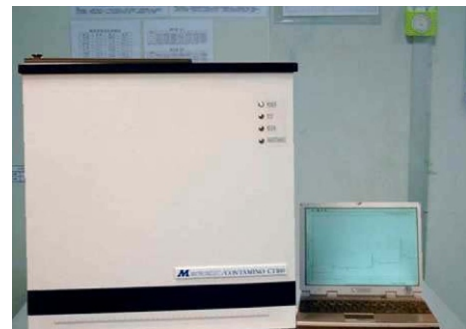
2-Dimensional Measure Instrument



Hole Diameter Inspection Machine



Blind Hole Tester



Ionic Contaminant Tester



X-Ray Fluorescence instrument



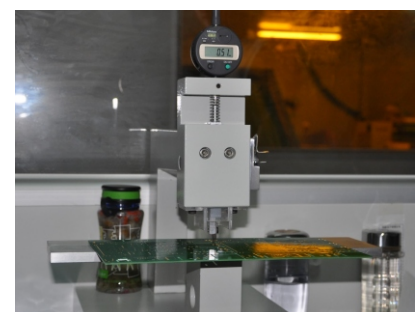
Impedance Tester



Universal Tester

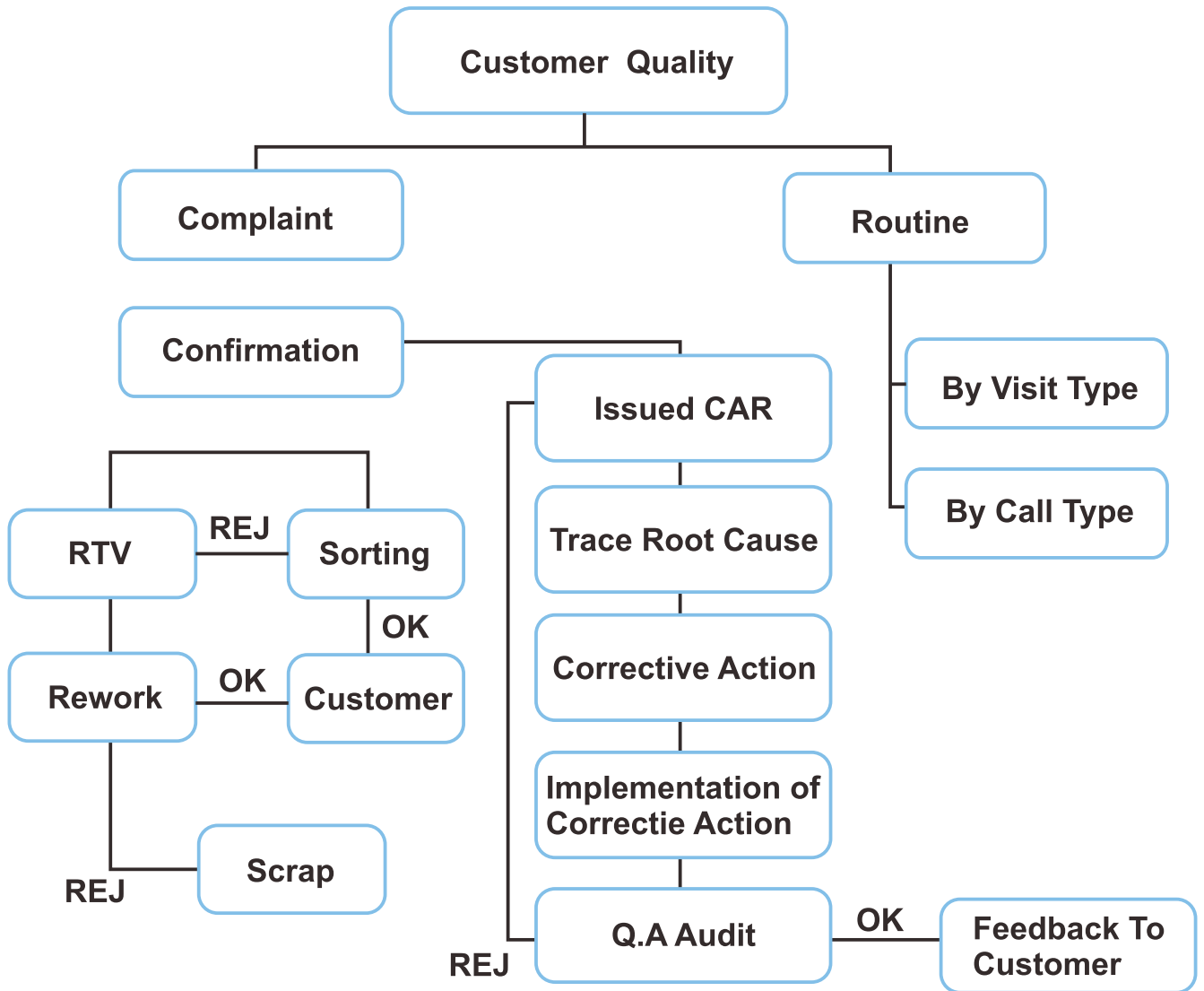


Thermal Shock Tester (P50)

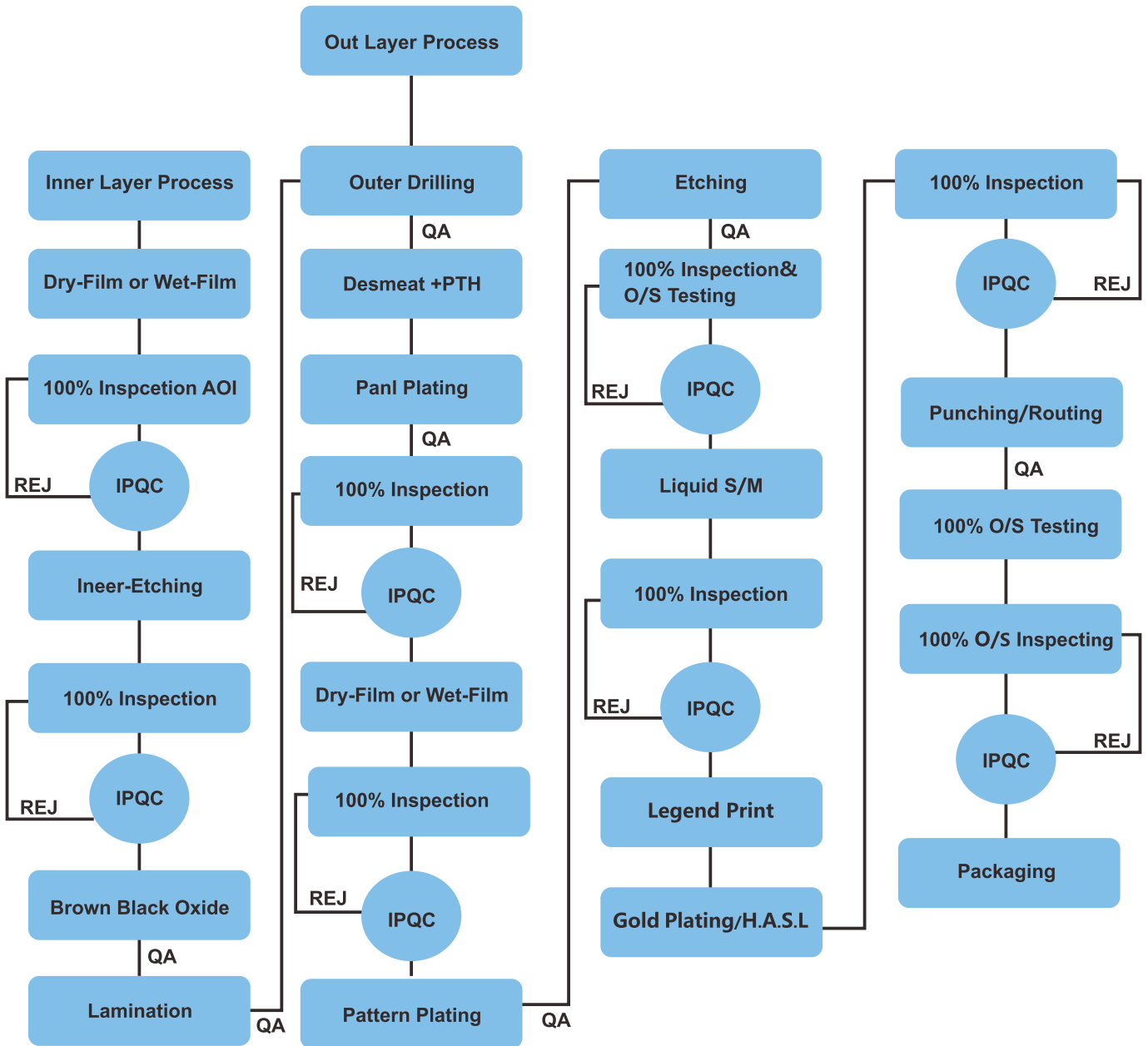


V-cut Depth Tester

Quality Control System



Process Flow Chart



Production Capability

Items	FR4 PCB	MPCPB	Ceramic PCB	Rigid-flex	Flexible Circuit
Max Layer Count	32 Layer	10 Layers	TickFilm: 10L; DCB: 2L	16 Layers	10 Layers
Minimum Board Thickness	5.5 mil (0.13mm) (1L)	12 mil (0.3mm)	TF: 10 mil (0.25mm) DCB: 12mil (0.30mm)	N/M	2mil (0.05mm)
	6.7 mil (0.17mm) (2L)	24 mil (0.6mm)	TF: 11 mil (0.28mm) DCB: 16mil (0.40mm)	12mil (0.30mm)	4mil (0.10mm)
	16 mil (0.4mm) (4 L)	40 mil (1.0mm)	13.5 mil (0.34mm)	16 mil (0.40mm)	8mil (0.20mm)
	24 mil (0.6mm) (6 L)	48 mil (1.2mm)	18 mil (0.46mm)	20 mil (0.50mm)	12mil (0.30mm)
	32 mil (0.8mm) (8 L)	62 mil (1.6mm)	32 mil (0.81mm)	28 mil (0.70mm)	16 mil (0.40mm)
	40 mil (1.0mm) (10 L)	79 mil (2.0mm)	42 mil (1.05mm)	36 mil (0.9mm)	24 mil (0.60mm)
Max Board Thickness	236 mil (6.0mm) for 2L 315 mil (8.0mm) for 4L & >4L	157 mil (4.0mm)	95 mil (2.4mm)	157 mil (4.0mm)	80 mil(2.0mm)
Max Board Dimension	610*610mm, or 100*1,300mm	610*1,625mm	138*178mm	480*480mm	480*480mm
Max Conductor thickness	20 OZ (0.70mm)	10 OZ (0.35mm)	TF: 13um; DCB: 0.30mm	2 OZ (70um)	4 OZ (140um)
Minimum conductor thickness	1/2 OZ (18um)		TF: 10um; DCB: 0.10mm	1/2 OZ (18um)	1/3 OZ (12um)
Min Trace Width/Space	Normal: 4/4mil; HDI:(3/3mil)	4/4mil (0.1/0.10mm)	10/10 mil (0.3/0.30mm)	4/4mil (0.1/0.10mm)	3/3mil (0.075/0.075mm)
Min Hole Diameter	4 mil (0.1mm)	10 mil (0.25mm)	4 mil (0.1mm)	4 mil (0.1mm)	4 mil (0.1mm)
Min Hole Spacing	12 mil (0.3mm)	16 mil (0.4mm)	NPTH: 16 mil (0.3mm) PTH: 20 mil (0.5mm)	NPTH: 16 mil (0.3mm) PTH: 20 mil (0.5mm)	NPTH: 16 mil (0.3mm) PTH: 20 mil (0.5mm)
Max Aspect Ratio	6:1	12:1	8:1	8:1	8:1
Min Solder	HDI: 10 mil	14mil (0.35mm)	10 mil (0.25mm)	10 mil (0.25mm)	10 mil (0.25mm)

Production Capability

Items	FR4 PCB	MCPCB	Ceramic PCB	Rigid-flex	Flexible Circuit
Min Solder PAD Dia	HDI: 10 mil (0.25mm) Normal: 14mil (0.35mm)	14 mil (0.35mm)	10 mil (0.25mm)	10 mil (0.25mm)	10 mil (0.25mm)
Min PAD Ring (Single Side)	3 mil (0.075mm)		6mil (0.15mm)	3 mil (0.075mm)	
PTH Wall Thickness	0.48mil (12 um) for HDI; 0.59mil (15um) for normal		TF: 4mil (10um) DCB: N/M	0.59mil (15um) for normal	
PTH Dia Tolerance	± 3 mil (0.075mm)		± 4 mil (0.10mm)	± 3 mil (0.075mm)	
NPTH Dia Tolerance	±2 mil (0.05mm)		± 2 mil (0.05mm)	±2 mil (0.05mm)	
Hole Position Deviation	±2 mil (0.05mm)	±3 mil (0.075mm)	±4 mil (0.10mm)	±4 mil (0.10mm)	±4 mil (0.10mm)
Outline Tolerance	CNC: ± 6 mil (0.15mm)	CNC: ± 6 mil (0.15mm)	Laser: +0.20mm/-0.05mm	Laser: +0.15mm/-0.05mm	Laser: +0.15mm/-0.05mm
	Die Punch: ± 4 mil (0.1mm)	Die Punch: ± 6 mil (0.15mm)	Die Punch: +0.25mm/-0.2mm	Die Punch: +0.10mm/-0.2mm	Die Punch: +0.10mm/-0.2mm
Min Soldermask Bridge	HDI: 6 mil (0.15mm); Normal: 8mil (0.2mm)	8 mil (0.20mm)	12 mil (0.3mm)	12 mil (0.3mm)	12 mil (0.3mm)
Min BAG PAD Margin	5 mil (0.125mm)		12 mil (0.3mm)	12 mil (0.3mm)	12 mil (0.3mm)
Impedance Controlled	Normal: ± 10% value ≤ 50 Ohm; ±5 OhmN/M	N/M	N/M	Normal: ± 10% value ≤ 50 Ohm; ±5 Ohm	
Thermal Conductivity (W/m.K or W/m.C)	0.30-0.45	Normal: 0.8~1.0, 1.5 High: 2.0, 3.0	Al2O3: 24; AlN/BeO: ≥170	0.30-0.45	
Dielectric Strength	> 1.3 KV /mm		≥15 KV/mm	≥1.3 KV/mm	≥1.35 KV/mm
Wrap&Twist	≤ 0.75%		≤ 3%	≤ 1%	≤ 1%
Flammability	94V-0				
Thermal Stress	3 x 10 Sec @ 280 °C				
Surface Treatment	ENIG, Flash Gold, Hard Gold Finger, Gold Plating(50mil), Gold finger, Selected Gold plating, ENEPIG, ENIPIG; HAL, HASL(LF), OSP, Silver Imm., Tin Imm		TF: AgPd, AuPd DCB: Ni plating, ENIG	ENIG, Flash Gold, Hard Gold Finger, Gold Plating(50mil), Gold finger, Selected Gold plating, ENEPIG, ENIPIG	

Lead time

Beside normal lead time, we also have expedite service, such as 1Day for 2Layers, 2D for 4L, 3D for 6L, 4D for 8L FR4 PCB.

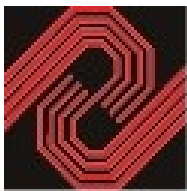
Prototype

	MCPCB	Ceramic PCB	Flex Circuit	HDI	Rigid flex	FR4 PCB
1L	3-5D	3-4W	3-5D	N/A	N/A	4-6D
2L	2-3W	4-5W	4-6D		3-4W	5-7D
4L	3-4W	5-6W	6-8D	3-4W	3-4W	8-10D
6L	4-5W	5-6W	7-9D		4-5W	10-12D
8L	4-5W	5-6W	10-12D		5-6W	12-15D
10L	4-5W	5-6W	12-15D		5-6W	3-4W
>10L	N/A	N/A	3-5W		4-5W	6-8W

Mass Production

	MCPCB	Ceramic PCB	FR4 PCB	HDI	Rigid flex	Flex Circuit
1L	1-1.5W	4-5W	4-6D	N/A	N/A	4-6D
2L	3-4W	5-6W	5-8D		3-4W	5-7D
4L	3-4W	5-6W	8-12D	4-6W	3-4W	8-10D
6L	4-5W	5-6W	8-12D		4-5W	10-12D
8L	4-5W	6-7W	12-16D		5-6W	12-15D
10L	5-6W	6-7W	18-20D		5-6W	3-4W
>10L	N/A	N/A	3-5W		5-7W	6-8W

Our Customers



Environment

Best Technology highly respects the environmental policy, as a member of the earth, that is no excuse of discharged hazardous wastes into our life circumstance. Everybody in our company is aware of this importance and strictly follow up ISO 14001 environmental management system. Best continues to work with all of our suppliers of materials that could be affected by the new RoHS compliance statutes.

Concerning environmental protection is one of the key policies in our MCPCB & FR4 PCB production system, we are doing RoHS standard boards, and built up an in-house sewage treatment system, and adopt way to reduce sewage demission, to make a much better working & life environment for all of people on the earth.



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